In the claims:

For the Examiner's convenience, all pending claims are presented below with changes shown in accordance with the mandatory amendment format.

1. (Currently Amended) An apparatus, comprising:

an absorber section of a heat pipe attached to a first end of a base of the heat pipe to remove heat from a heat spreader, wherein the absorber section having a size of at least a surface area of the heat spreader; ~~and~~

a dissipater section of the heat pipe attached to a second end of the base of the heat pipe, wherein a width of the dissipater section is greater than a width of the base of the heat pipe, and the dissipater section having a size of at least a surface area of the absorber section; and

a plurality of fins formed of the second end of the base, the plurality of fins attached to a bottom surface of the dissipater section, the fins having a length approximately equal to the width of the base.

2.-12. (Cancelled)

13. (Currently Amended) A computer system, comprising:

a central processing unit (CPU);

a heat absorber attached to a first end of a base of a heat pipe and having a size of at least a surface area of a heat spreader; ~~and~~

a heat dissipater attached to a second end of the base of the heat pipe, wherein a width of the heat dissipater is greater than a width of the base of the heat pipe, and the heat dissipater having a size of at least a surface area of the heat absorber; and

a plurality of fins formed on the second end of the base, the plurality of fins attached to a bottom surface of the heat dissipater, the plurality of fins having a length approximately equal to the width of the base.

14.-18. (Cancelled)

19. (Previously Presented) The apparatus of claim 1, wherein the absorber section and the base of the heat pipe are formed of a thermally conductive material selected from the group including copper, a copper allow, and aluminum.

20. (Previously Presented) The apparatus of claim 1, wherein the absorber section is attached to the heat spreader by a thermal interface material.

21. (Currently Amended) The apparatus of claim 1 ~~claim 6~~, wherein the plurality of fins are formed of a thermally conductive material selected from the group including copper, a copper alloy, and aluminum.

22. (Previously Presented) The apparatus of claim 1, wherein the absorber section and the dissipater section are the same size.

23. (Previously Presented) The system of claim 13, wherein the heat absorber and the base of the heat pipe are formed of a thermally conductive material selected from the group including copper, a copper allow, and aluminum.

24. (Previously Presented) The system of claim 13, wherein the heat absorber is attached to the heat spreader by a thermal interface material.

25. (Previously Presented) The system of claim 13, wherein the heat absorber removes heat from the heat spreader.

26. (Currently Amended) The system of claim 13 ~~claim 17~~, further comprising a fan to direct air across at least one of the plurality of fins and the base of the heat pipe to dissipate heat produced by the CPU.

27. (Currently Amended) The system of claim 13 ~~claim 17~~, wherein the plurality of fins are formed of a thermally conductive material selected from the group including copper, a copper alloy, and aluminum.

28. (New) The apparatus of claim 1, wherein the absorber section removes heat from the heat spreader.

29. (New) The apparatus of claim 1, wherein a fan directs air across at least one of the plurality of fins and the base of the heat pipe to dissipate heat produced by a central processing unit (CPU) and absorbed by the heat absorber.